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-	218	"air egress"	USPAT;	2002/05/01 12:43
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-	41	"air egress" and adhesive	USPAT;	2002/04/25 17:56
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-	434	"vacuum metallization"	USPAT;	2002/04/25 17:56
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-	10	"vacuum metallization" and adhesive and (sticker or label)	USPAT;	2002/04/25 17:56
	210		US-PGPUB	
•	219	"vacuum metallization" and adhesive	USPAT;	2002/04/26 12:13
•		H005CC01#	US-PGPUB	
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